

**MBS Plastic-Encapsulate Bridge Rectifier****MB05S THRU MB10S General Purpose Bridge Rectifier****Features**

- $I_{F(AV)}$ 1A
- V_{RRM} 50V-1000V
- High surge current capability
- Glass passivated chip

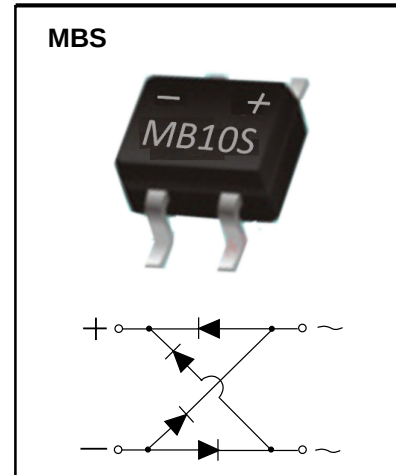
Applications

- General purpose 1 phase Bridge rectifier applications

Marking

- MBXXS

X : From 05 To 10

**Limiting Values (Absolute Maximum Rating)**

Item	Symbol	Unit	Conditions	MB						
				05S	1S	2S	4S	6S	8S	10S
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	200	400	600	800	1000
Maximum RMS Voltage	V_{RMS}	V		35	70	140	280	420	560	700
Average Rectified Output Current	I_O	A	60Hz sine wave, R-load, $T_a=40^{\circ}\text{C}$	1.0						
Surge(Non-repetitive) Forward Current	I_{FSM}	A	60Hz half sine wave, 1 cycle, $T_j=25^{\circ}\text{C}$	35						
Current Squared Time	I^2t	A^2S	$1\text{ms} \leq t < 8.3\text{ms}$ $T_j=25^{\circ}\text{C}$, Rating of per diode	5.08						
Operation Junction and Storage Temperature Range	T_J, T_{stg}	$^{\circ}\text{C}$		-55 ~ +150						

Electrical Characteristics ($T_a=25^{\circ}\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition	Max
Peak Forward Voltage	V_{FM}	V	$I_{FM}=1.0\text{A}$, Pulse measurement, Rating of per diode	1.0
Peak Reverse Current	I_{RRM}	μA	$V_{RM}=V_{RRM}$, Pulse measurement, Rating of per diode	10
Thermal Resistance	$R_{\theta J-A}$	$^{\circ}\text{C/W}$	Between junction and ambient, On alumina substrate	76
			Between junction and ambient, On glass-epoxy substrate	134
	$R_{\theta J-L}$		Between junction and lead	20

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

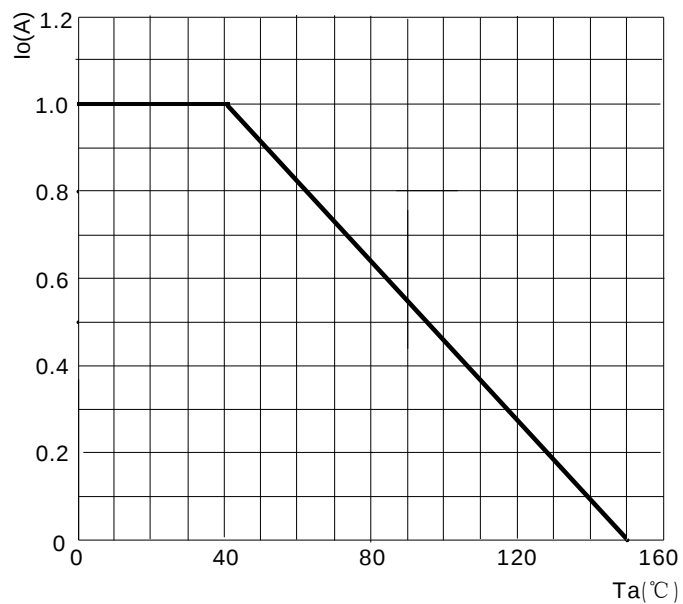


FIG.2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

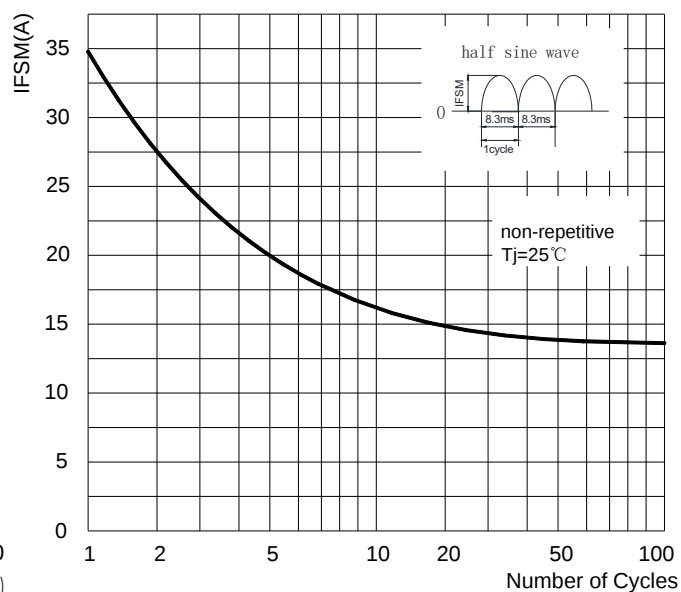


FIG.3: TYPICAL FORWARD CHARACTERISTICS

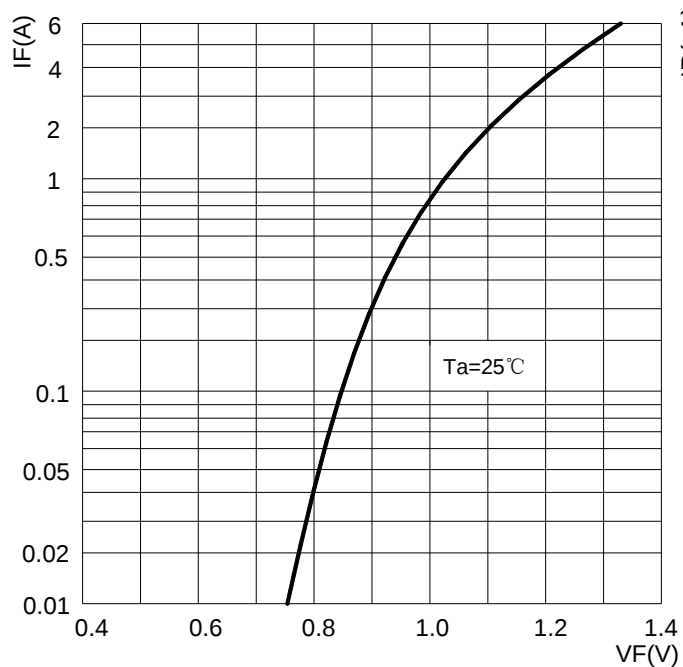
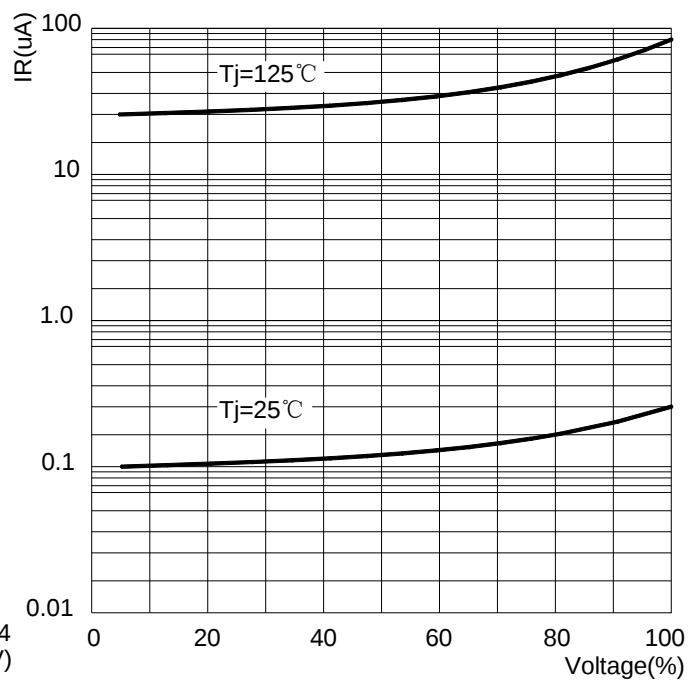
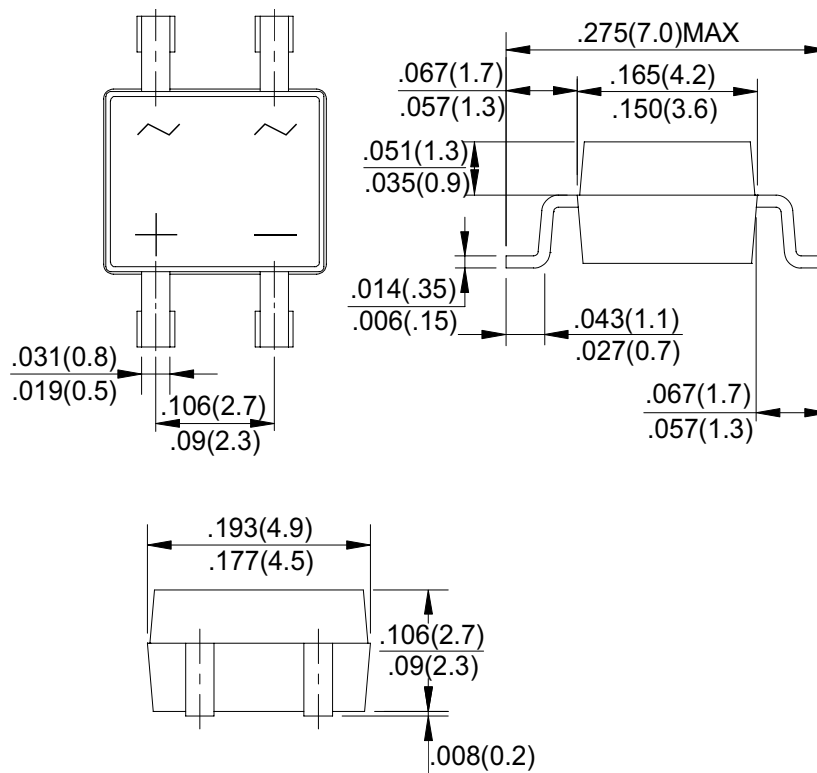


FIG.4: TYPICAL REVERSE CHARACTERISTICS

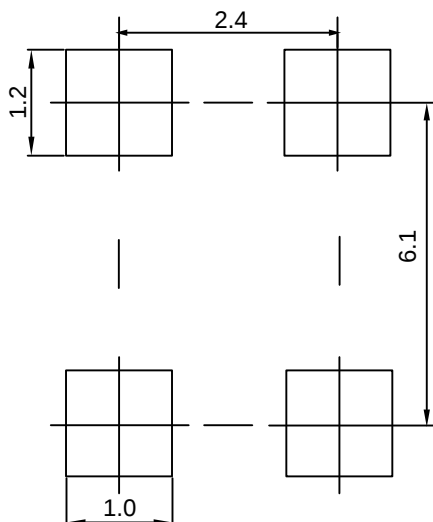


MBS Package Outline Dimensions



Dimensions in inches and (millimeters)

MBS Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

NOTICE

JSCJ reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. JSCJ does not assume any liability arising out of the application or use of any product described herein.

Reel Taping Specifications For Surface Mount Devices-MBS

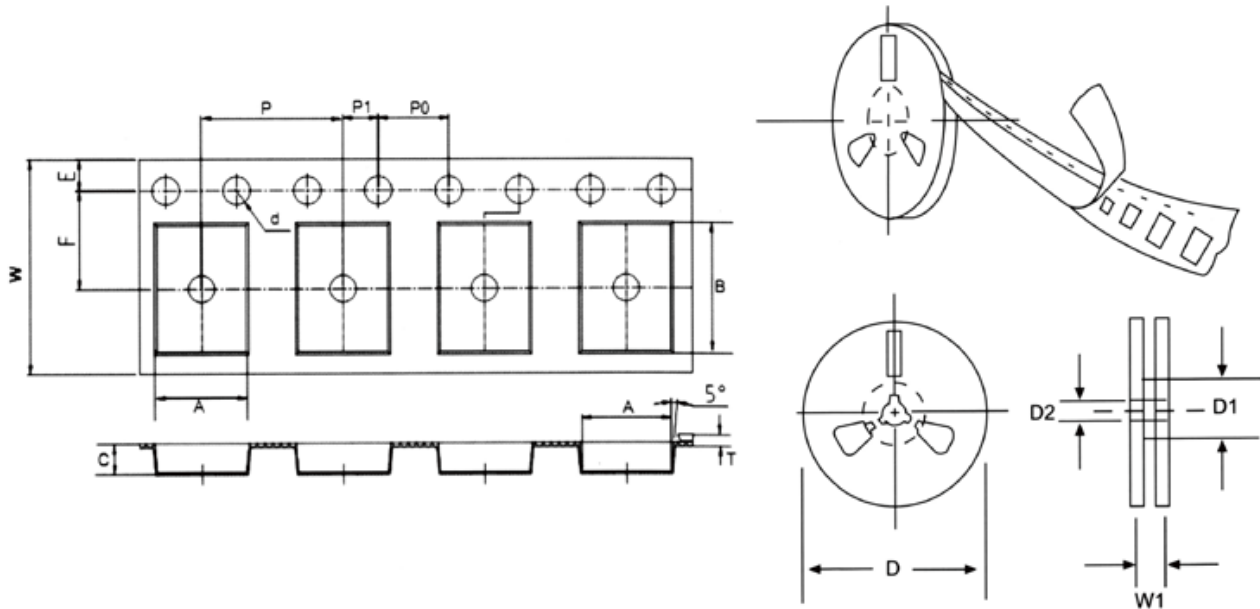


FIG:CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	MBS mm(inch)
Carrier width	A	5.05+0.1(0.198+0.004)
Carrier length	B	7.22+0.1(0.284+0.004)
Carrier depth	C	2.88+0.1(0.113+0.004)
Sprocket hole	d	1.55±0.05 (0.061±0.002)
Reel outside diameter	D	330±2.0(13±0.079)
Reel inner diameter	D1	75 ±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13+0.5(0.512+0.020)
Strocket hole position	E	1.75+0.1(0.069+0.004)
Punch hole position	F	5.50+0.05(0.217+0.002)
Punch hole pitch	P	8.0+0.1(0.315+0.004)
Sprocket hole pitch	P0	4.0+0.1(0.157+0.004)
Embossment center	P1	2.0+0.1(0.079+0.004)
Totall tape thickness	T	0.20-0.70(0.080-0.028)
Tape width	W	12.0+0.3/-0.1(0.472+0.004)
Reel width	W1	16.8+2.0(0.661+0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.